



N-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

BV _{DSS}	R _{DS(ON)} Max	I _D Max T _A = +25°C
60V	5.0Ω @ V _{GS} = 10V	0.26A
000	5.3Ω @ V _{GS} = 4.5V	0.25A

Features and Benefits

- Low On-Resistance
- Low Input Capacitance
- Fast Switching Speed
- Low Input/Output Leakage
- ESD Protected up to 2kV
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- For automotive applications requiring specific change control (i.e. parts qualified to AEC-Q100/101/200, PPAP capable, and manufactured in IATF 16949 certified facilities), please contact us or your local Diodes representative. https://www.diodes.com/quality/product-definitions/

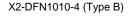
Description and Applications

This MOSFET has been designed to minimize the on-state resistance (RDS(ON)) yet maintain superior switching performance, making it ideal for high efficiency power management applications.

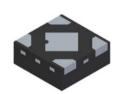
Load switch

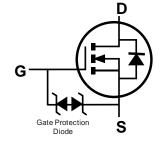
Mechanical Data

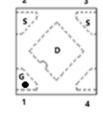
- Package: X2-DFN1010-4
- Package Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: See Diagram
- Terminals: Finish NiPdAu Annealed over Copper Leadframe. Solderable per MIL-STD-202, Method 208 @4)
- Weight: 0.0015 grams (Approximate)











Equivalent Circuit

Pin-Out Top View

Ordering Information (Note 4)

Part Number	Packago	Packing			
Fait Nullibel	Package	Qty.	Carrier		
DMN65D7LFR4-7	X2-DFN1010-4 (Type B)	5000	Tape & Reel		

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/

Marking Information

57 **YWX** 57 = Product Type Marking Code YWX = Date Code Marking

Y = Year (ex: 1 = 2021)

W = Week (ex: a = Week 27; z Represents Week 52 and 53) X = Internal Code (ex: U = Monday)

Date Code Key

2410 0040 11	,												
Year		2020	2021	2022	2023	2024	2025	2026	2027	2028	2029	2030	2031
Code		0	1	2	3	4	5	6	7	8	9	0	1

V	Neek	1-26	27-52	53
(Code	A-Z	a-z	Z

Internal Code	Sun	Mon	Tue	Wed	Thu	Fri	Sat
Code	Т	U	V	W	Χ	Υ	Z

DMN65D7LFR4 Document number: DS42794 Rev. 3 - 2



Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit	
Drain-Source Voltage	VDSS	60	V		
Gate-Source Voltage	V_{GSS}	±20	V		
Continuous Drain Current (Note 6) V _{GS} = 10V	Steady State	T _A = +25°C T _A = +70°C	lD	0.26 0.21	А
Maximum Continuous Body Diode Forward Current	(Note 6)		Is	0.26	Α
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%)			I _{DM}	1	Α
Pulsed Source Current (10µs Pulse, Duty Cycle = 1	l%)		lsм	1	Α

Thermal Characteristics (@TA = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit
Total Power Dissipation (Note 5)		PD	0.6	W
Thermal Resistance, Junction to Ambient (Note 5)	Steady State	Reja	213	°C/W
Total Power Dissipation (Note 6)		PD	0.7	W
Thermal Resistance, Junction to Ambient (Note 6)	Steady State	Reja	174	°C/W
Operating and Storage Temperature Range	·	T _{J,} T _{STG}	-55 to +150	°C

Electrical Characteristics (@TA = +25°C, unless otherwise specified.)

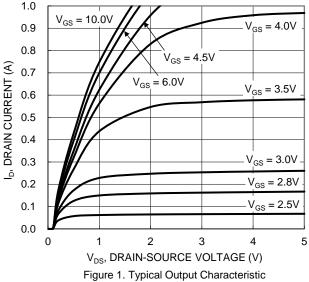
			_			
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 7)					1	
Drain-Source Breakdown Voltage	BV _{DSS}	60	_	_	V	$V_{GS} = 0V$, $I_D = 10\mu A$
Zero Gate Voltage Drain Current	IDSS	_	_	1.0	μΑ	$V_{DS} = 60V$, $V_{GS} = 0V$
Gate-Source Leakage	Igss		_	±10	μΑ	$V_{GS} = \pm 20V$, $V_{DS} = 0V$
ON CHARACTERISTICS (Note 7)						
Gate Threshold Voltage	V _{GS(TH)}	1.0	_	2.5	V	$V_{DS} = V_{GS}, I_D = 250 \mu A$
Static Drain-Source On-Resistance	D		1.2	5.0	Ω	$V_{GS} = 10V, I_{D} = 40mA$
Static Drain-Source On-Resistance	RDS(ON)	_	1.4	5.3	12	$V_{GS} = 4.5V, I_{D} = 35mA$
Diode Forward Voltage	Vsp	_	0.85	1.1	V	V _G S = 0V, I _S = 300mA
DYNAMIC CHARACTERISTICS (Note 8)						
Input Capacitance	C _{iss}	_	41	_	рF	.,
Output Capacitance	Coss		4.5	_	рF	V _{DS} = 30V, V _{GS} = 0V f = 1.0MHz
Reverse Transfer Capacitance	Crss	_	2.7	_	pF	1 = 1.0IVII IZ
Gate Resistance	Rg	_	224	_	Ω	$f = 1MHz$, $V_{GS} = 0V$, $V_{DS} = 0V$
Total Gate Charge (VGS = 4.5V)	Qg		0.51		nC	
Total Gate Charge (Vgs = 10V)	Qg		1.04	_	nC	V _{DS} = 15V, I _D = 200mA
Gate-Source Charge	Qgs	_	0.16	_	nC	VDS = 15V, ID = 200MA
Gate-Drain Charge	Q_{gd}		0.18	_	nC	
Turn-On Delay Time	t _D (ON)	_	6.9	_	ns	
Turn-On Rise Time	t _R	_	5.8	_	ns	V _{DD} = 30V, V _{GS} = 10V,
Turn-Off Delay Time	t _{D(OFF)}	_	37.8	_	ns	$R_G = 150\Omega$, $I_D = 200mA$
Turn-Off Fall Time	t _F	_	14.3	_	ns	
Reverse Recovery Time	trr	_	19	_	ns	IF =1A, di/dt = 100A/µs
Reverse Recovery Charge	Q _{RR}	_	9	_	nC	IF =1A, di/dt = 100A/µs

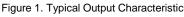
5. Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.

^{6.} Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate.
7. Short duration pulse test used to minimize self-heating effect.

^{8.} Guaranteed by design. Not subject to product testing.







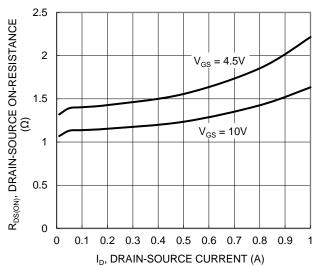


Figure 3. Typical On-Resistance vs. Drain Current and Gate Voltage

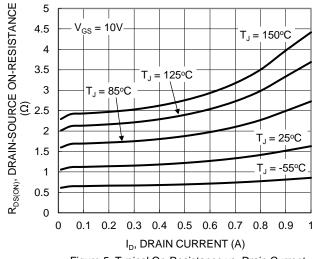
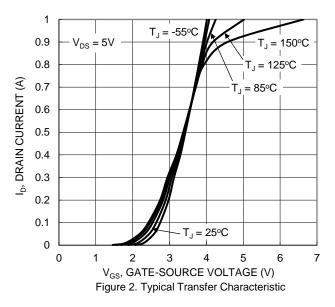
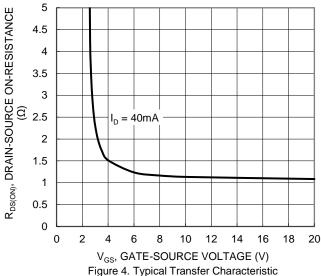


Figure 5. Typical On-Resistance vs. Drain Current and Junction Temperature





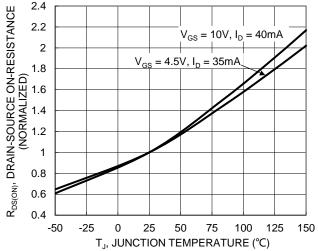


Figure 6. On-Resistance Variation with Junction Temperature



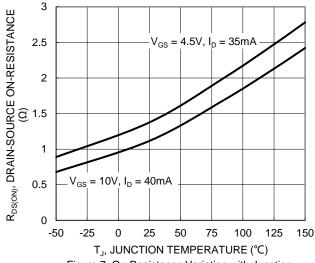


Figure 7. On-Resistance Variation with Junction Temperature

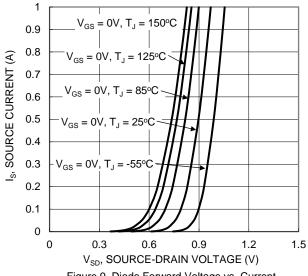


Figure 9. Diode Forward Voltage vs. Current

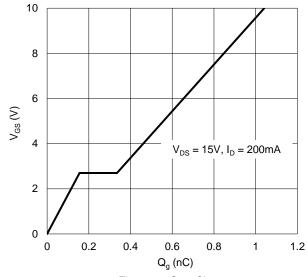


Figure 11. Gate Charge

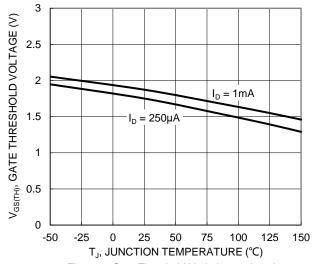


Figure 8. Gate Threshold Variation vs Junction Temperature

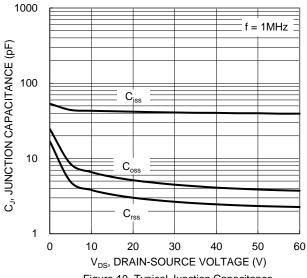


Figure 10. Typical Junction Capacitance

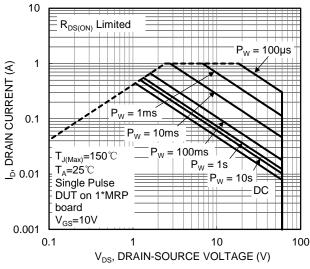


Figure 12. SOA, Safe Operation Area



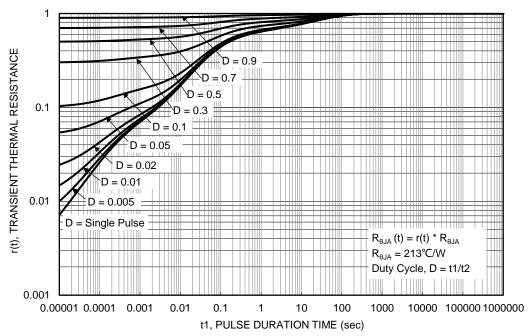


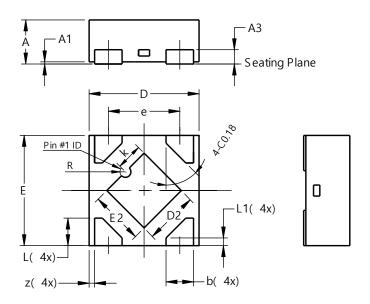
Figure 13. Transient Thermal Resistance



Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

X2-DFN1010-4 (Type B)

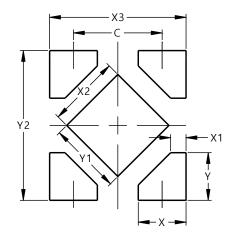


X2-	DFN1010)-4 (Typ	e B)
Dim	Min	Max	Тур
Α	-	0.40	0.39
A1	0.00	0.05	0.02
A3	-	-	0.13
b	0.20	0.30	0.25
D	0.95	1.05	1.00
D2	0.43	0.53	0.48
Е	0.95	1.05	1.00
E2	0.43	0.53	0.48
е	-	-	0.65
k	0.19	0.29	0.24
L	0.20	0.30	0.25
L1	0.02	0.12	0.07
R	0.02	0.08	0.05
Z	-	-	0.050
All	Dimensi	ons in	mm

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

X2-DFN1010-4 (Type B)



Dimensions	Value (in mm)
С	0.650
X	0.350
X1	0.112
X2	0.530
Х3	1.00
Y	0.350
Y1	0.530
Y2	1.100



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